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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chen-Hua Yu	05/18/2006
Minghsing Tsai	05/18/2006
Yi-Li Hsiao	05/19/2006

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Co., Ltd.	
Street Address:	No. 8, Li-Hsin Road 6	
Internal Address:	Science-Based Industrial Park	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code:	300-77	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11419933

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ATTORNEY DOCKET NUMBER:	N1085-00433
NAME OF SUBMITTER:	Steven E. Koffs

Total Attachments: 2

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REEL: 017676 FRAME: 0962

PATENT 500107541

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PATENT REEL: 017676 FRAME: 0963 Serial No. 11/419,933 Filed: May 23, 2006

ATTORNEY DOCKET NO. 2006.0095/1085.00433

ASSIGNMENT AND AGREEMENT

For value received, we, Chen-Hua Yu, Minghsing Tsai, and Yi-Li Hsiao, hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd., with its principal place of business located at No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to PROCESS APPARATUSES described in a non-provisional application for Letters Patent of the United States and provisional Application Serial No. 60/747,442 filed on May 17, 2006 and all the rights and privileges in said applications, and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof, or claiming priority therefrom that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize Taiwan Semiconductor Manufacturing Co., Ltd. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Taiwan Semiconductor Manufacturing Co., Ltd. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

We request that any and all patents for said inventions be issued to Taiwan Semiconductor Manufacturing Co., Ltd. in the United States and in all countries foreign to the United States, or to such nominees as Taiwan Semiconductor Manufacturing Co., Ltd. may designate.

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PATENT REEL: 017676 FRAME: 0964

RECORDED: 05/24/2006

ATTORNEY DOCKET NO. 2006.0095/1085.00433

We agree that, when requested, we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

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PATENT REEL: 017676 FRAME: 109965